PCN Number:	20151215005				PCN Da	ate:	12/16/2015	
Title: Datasheet fo	or TMP175 and T	MP75						
ustomer Contact: PCN Manager				De	Dept:		Quality Services	
Change Type:					_		-	
Assembly Site		Design			Wafer	⁻ Bum	p Site	
Assembly Process			et		Wafer	er Bump Material		
Assembly Materials		Part num	ber change		Wafer	⁻ Bum	Bump Process	
	Mechanical Specification					Fab Site		
Packing/Shipping/Labeling		Test Proc	ess				Fab Materials	
					Wafer	⁻ Fab I	Process	
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he product datasheet he following change	.,			' -				
TEXAS						тир	175, TMP75	
INSTRUMENTS			SBOS288	-JANU	ARY 2004-R		DECEMBER 2015	
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Changes from Revision K	(April 2015) to Revisi	on L					Page	
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For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

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